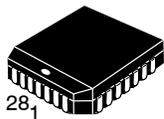


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

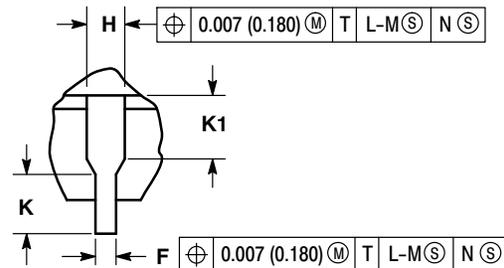
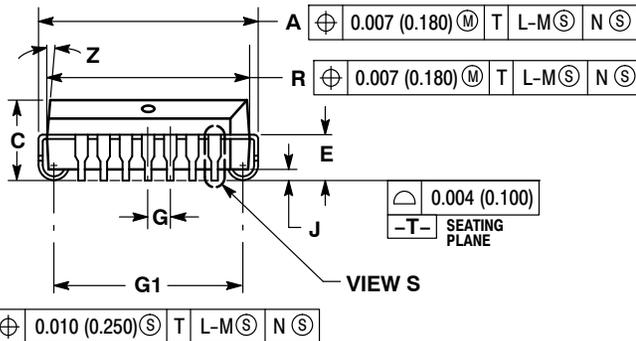
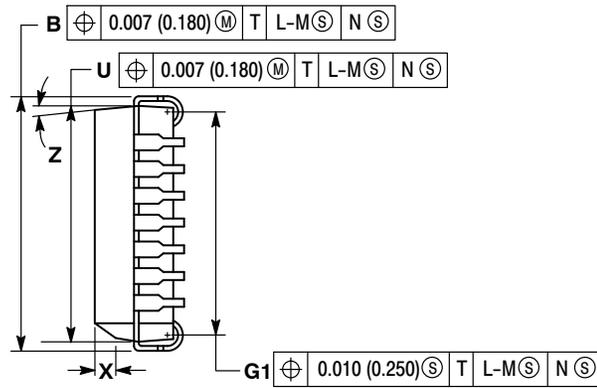
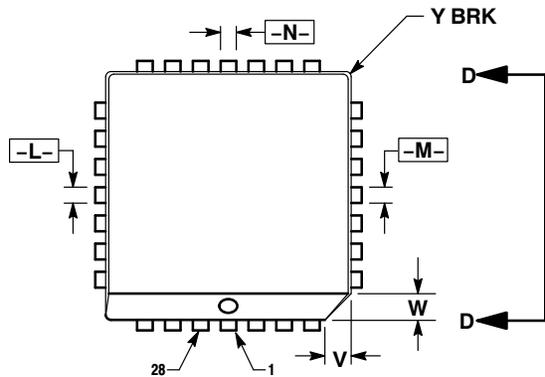
ON Semiconductor®



SCALE 1:1

28 LEAD PLLC  
CASE 776-02  
ISSUE F

DATE 29 JUL 2008

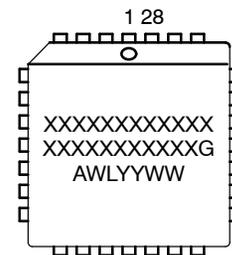


NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

| DIM | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
|     | MIN       | MAX   | MIN         | MAX   |
| A   | 0.485     | 0.495 | 12.32       | 12.57 |
| B   | 0.485     | 0.495 | 12.32       | 12.57 |
| C   | 0.165     | 0.180 | 4.20        | 4.57  |
| E   | 0.090     | 0.110 | 2.29        | 2.79  |
| F   | 0.013     | 0.021 | 0.33        | 0.53  |
| G   | 0.050 BSC |       | 1.27 BSC    |       |
| H   | 0.026     | 0.032 | 0.66        | 0.81  |
| J   | 0.020     | ---   | 0.51        | ---   |
| K   | 0.025     | ---   | 0.64        | ---   |
| R   | 0.450     | 0.456 | 11.43       | 11.58 |
| U   | 0.450     | 0.456 | 11.43       | 11.58 |
| V   | 0.042     | 0.048 | 1.07        | 1.21  |
| W   | 0.042     | 0.048 | 1.07        | 1.21  |
| X   | 0.042     | 0.056 | 1.07        | 1.42  |
| Y   | ---       | 0.020 | ---         | 0.50  |
| Z   | 2°        |       | 10°         |       |
| G1  | 0.410     | 0.430 | 10.42       | 10.92 |
| K1  | 0.040     | ---   | 1.02        | ---   |

GENERIC MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

|                  |                           |  |
|------------------|---------------------------|--|
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| STATUS:          | ON SEMICONDUCTOR STANDARD |  |
| NEW STANDARD:    |                           |  |
| DESCRIPTION:     | 28 LEAD PLLC              | PAGE 1 OF 2  |

